The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A film-like article comprising:

a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article, the thin film integrated circuit comprising a thin film transistor having a semiconductor film of thickness of 0.2 μm or less; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit and the antenna are mounted inside the film-like article.

2. (Currently Amended) A film-like article comprising:

a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit is mounted inside the film-like article, and

the antenna is mounted on a surface of the film-like article.

3. (Currently Amended) A film-like article according to Claim 1,

wherein when the thickness of the film-like article is D, ~~the position~~ a position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2)\cdot D - 30\ \mu m < X < (1/2)\cdot D + 30\ \mu m$.

4. (Currently Amended) A film-like article according to Claim 2,

wherein when the thickness of the film-like article is D, ~~the position~~ a position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2)\cdot D - 30\ \mu m < X < (1/2)\cdot D + 30\ \mu m$.

5. (Currently Amended) A film-like article comprising:

a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit and the antenna are mounted on a surface of the film-like article.

6. (Currently Amended) A film-like article comprising:

a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit is mounted on a surface of the film-like article, and

the antenna is mounted inside the film-like article.

7. (Currently Amended) A film-like article comprising a thin film integrated circuit ~~which can store~~ capable of storing information described on the film-like article, the thin film integrated circuit comprising a thin film transistor having a semiconductor film of thickness of 0.2 μm or less,

wherein the film-like article is provided with a depression, and

the thin film integrated circuit includes an antenna.

8. (Currently Amended) A film-like article according to Claim 1, further comprising

a substrate,

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

9. (Currently Amended) A film-like article according to Claim 2, further comprising

a substrate,

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

10. (Currently Amended) A film-like article according to Claim 5, further comprising:

a substrate,

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

11. (Currently Amended) A film-like article according to Claim 6, further comprising:

a substrate,

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

12. (Currently Amended) A film-like article according to Claim 7, further comprising:

a substrate,

wherein an opening with slits is provided in ~~a connection area between the thin film integrated circuit and the antenna.~~ the substrate,

wherein the thin film integrated circuit is electrically connected to the antenna through the opening in the substrate.

13. (Original) A film-like article according Claim 1,
wherein the thin film integrated circuit has light-transmitting characteristic.

14. (Original) A film-like article according Claim 2,
wherein the thin film integrated circuit has light-transmitting characteristic.

15. (Original) A film-like article according Claim 5,
wherein the thin film integrated circuit has light-transmitting characteristic.

16. (Original) A film-like article according Claim 6,
wherein the thin film integrated circuit has light-transmitting characteristic.

17. (Original) A film-like article according Claim 7,
wherein the thin film integrated circuit has light-transmitting characteristic.

18. (Original) A film-like article according to Claim 1,
wherein the thin film integrated circuit has an insulating film containing nitrogen.

19. (Original) A film-like article according to Claim 2, wherein the thin film integrated circuit has an insulating film containing nitrogen.

20. (Original) A film-like article according to Claim 5, wherein the thin film integrated circuit has an insulating film containing nitrogen.

21. (Original) A film-like article according to Claim 6, wherein the thin film integrated circuit has an insulating film containing nitrogen.

22. (Original) A film-like article according to Claim 7, wherein the thin film integrated circuit has an insulating film containing nitrogen.

23. (Original) A film-like article according to Claim 1, wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm.

24. (Original) A film-like article according to Claim 2, wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm.

25. (Original) A film-like article according to Claim 5, wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm.

26. (Original) A film-like article according to Claim 6, wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm.

27. (Original) A film-like article according to Claim 7,

wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm.

28. (Original) A film-like article according to Claim 1,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm^3 to 5×10^{20} atoms/cm^3.

29. (Original) A film-like article according to Claim 2,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm^3 to 5×10^{20} atoms/cm^3.

30. (Original) A film-like article according to Claim 5,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm^3 to 5×10^{20} atoms/cm^3.

31. (Original) A film-like article according to Claim 6,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm^3 to 5×10^{20} atoms/cm^3.

32. (Original) A film-like article according to Claim 7,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm^3 to 5×10^{20} atoms/cm^3.

33. (Original) A film-like article according to any one of Claims 28 to 32,

wherein the semiconductor film includes a source, a drain, and a channel region, and

the source, the drain, and the channel region are provided perpendicular to direction of bending the film-like article.

34. (Original) A film-like article according to Claim 1,

wherein the film-like article comprises a plurality of thin film integrated circuits, and

the plurality of thin film integrated circuits are integrated with antennas.

35. (Original) A film-like article according to Claim 2,

wherein the film-like article comprises a plurality of thin film integrated circuits, and

the plurality of thin film integrated circuits are integrated with antennas.

36. (Original) A film-like article according to Claim 5,

wherein the film-like article comprises a plurality of thin film integrated circuits, and

the plurality of thin film integrated circuits are integrated with antennas.

37. (Original) A film-like article according to Claim 6,

wherein the film-like article comprises a plurality of thin film integrated circuits, and

the plurality of thin film integrated circuits are integrated with antennas.

38. (Original) A film-like article according to Claim 7,

wherein the film-like article comprises a plurality of thin film integrated circuits, and

the plurality of thin film integrated circuits are integrated with antennas.

39. (Original) A film-like article according to Claim 1, wherein the film-like article is a business card.

40. (Original) A film-like article according to Claim 2, wherein the film-like article is a business card.

41. (Original) A film-like article according to Claim 5, wherein the film-like article is a business card.

42. (Original) A film-like article according to Claim 6, wherein the film-like article is a business card.

43. (Original) A film-like article according to Claim 7, wherein the film-like article is a business card.

44. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated ~~circuits~~ circuit; and

enfolding the thin film integrated circuits and the antenna in a base member of the film-like ~~article~~ article,

wherein each of the plurality of the thin film integrated circuits comprises a thin film transistor having a semiconductor film of thickness of 0.2 μm or less.

45. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated ~~circuits~~ circuit; and

mounting the thin film integrated circuits and the antenna on a surface of a base member of the film-like article.

46. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated ~~circuits~~ circuit; and

mounting the thin film integrated circuits and the antenna in a depression on a surface of a base member of the film-like ~~article~~ article,

wherein each of the plurality of the thin film integrated circuits comprises a thin film transistor having a semiconductor film of thickness of 0.2 μm or less.

47. (Currently Amended) A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

cutting the second substrate to cut out each of the plurality of thin film integrated circuits; and

enfolding ~~the thin film integrated circuit~~ each of the plurality of thin film integrated circuits in a base member of the film-like article,

forming an antenna on a surface of the base member of the film-like article so that the thin film integrated ~~circuits~~ circuit and the antenna are connected through an opening formed on the base member of the film-like article.

48. (Currently Amended) A method for manufacturing a film-like article, comprising the step of forming an antenna on a surface of a base member of the film-like article so that a plurality of thin film integrated circuits and the antenna are connected through an opening formed on the base member of the film-like article,

wherein [[a]] the plurality of thin film integrated circuits are formed over a first substrate,

the plurality of thin film integrated circuits are transferred to a second substrate, and

the second substrate is cut so as to cut out the plurality of thin film integrated ~~circuits~~ circuits,

wherein each of the plurality of the thin film integrated circuits comprises a thin film transistor having a semiconductor film of thickness of 0.2 μm or less.